



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Applicant of
Khandros et al.

Continued Prosecution Application
of Serial No. 08/984,615

Filed: December 3, 1997

For: **SEMICONDUCTOR CHIP PACKAGE
WITH CENTER CONTACTS**

Group Art Unit: 2815

Examiner: S. Clark

Date: September 10, 1998

Batch No. F86

Assistant Commissioner For Patents
Box Patent Application
Washington, D.C. 20231

Pre-Amended
RECEIVED
SEP 18 1998
10-7-98
GROUP 2100

PRELIMINARY AMENDMENT

Sir:

Prior to calculating the filing fee in the Continued Prosecution Application filed contemporaneously herewith, please amend the application as follows:

In the Claims:

Insert new claims 71-76 as follows:

71.11 A chip assembly as claimed in claim ~~61~~¹ wherein the contact leads include wire bonds.

72.12 A semiconductor chip assembly comprising:

(a) a semiconductor chip having a front surface defining the top of the chip, said front surface including a central region and a peripheral region surrounding said central region, whereby said central region is disposed inwardly of said peripheral region, said chip having central contacts disposed in said central region of said front surface;

C1

75

C